

ABSTRACT

A method of making a thermal management material for a circuit board panel comprising the steps of cutting a thermally conductive, rigid substrate from a larger sheet of heat conducting material, degreasing the thermally conductive substrate, mechanically abrading at least one surface of the thermally conductive substrate, acid cleaning the at least one abraded surface of the thermally conductive substrate, rinsing the thermally conductive substrate, passivating the at least one abraded surface of the thermally conductive substrate to render the at least one surface chemically inert, rinsing the thermally conductive substrate, drying the thermally conductive substrate and baking the thermally conductive substrate at an elevated temperature.